Unit: mm

2SC2671F

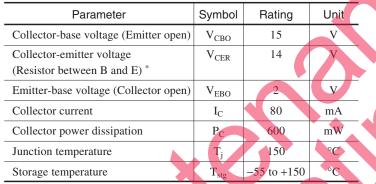
Silicon NPN epitaxial planar type

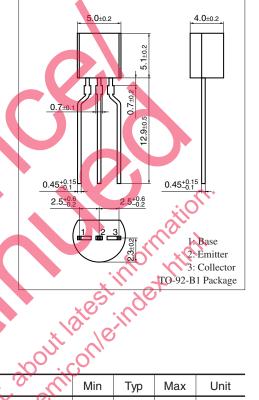
For UHF band low-noise amplification

Features

- Low noise figure NF
- \bullet High maximum unilateral power gain G_{UM}
- \bullet High transition frequency f_{T}

Absolute Maximum Ratings $T_a = 25^{\circ}C$



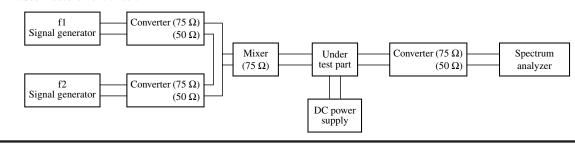


Note) *: $R_{BE} = 1 k\Omega$

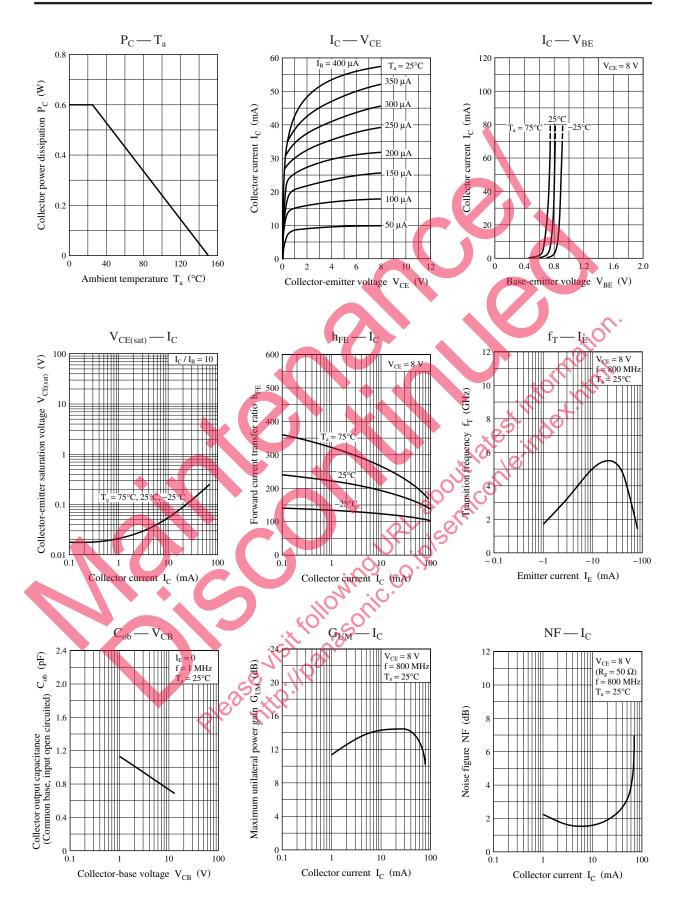
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{\rm EB} = 1 \text{ V}, I_{\rm C} = 0$			1	μΑ
Forward current transfer ratio	h _{FE}	$V_{\rm CE} = 8 \text{ V}, 1_{\rm C} = 40 \text{ mA}$	50	150	300	
Transition frequency	f _T	$V_{CE} = 8 V, I_C = 40 mA, f = 0.8 GHz$	3.5	5.5		GHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		0.8	1.5	pF
(Common base, input open circuited)		X				
Foward transfer gain	S _{21e} ²	$V_{CE} = 8$ V, $I_C = 40$ mA, $f = 0.8$ GHz	9	12		dB
Maximum unilateral power gain	GUM	$V_{CE} = 8 \text{ V}, I_{C} = 40 \text{ mA}, f = 0.8 \text{ GHz}$	10	13	15	dB
Noise figure	NF	$V_{CE} = 8 \text{ V}, I_C = 40 \text{ mA}, f = 0.8 \text{ GHz}$		2.0	3.2	dB
Second inter modulation distortion	IM ₂	$V_{CE} = 8 V, I_C = 40 mA, f_1 = 200 MHz$	50	60		dB
× ·		$f_2 = 500 \text{ MHz}, \text{ V}_0 = 100 \text{ dB}\mu/75 \Omega$				
Third inter modulation distortion *	IM ₃	$V_{CE} = 8 V, I_C = 40 mA, f_1 = 600 MHz$	75	86		dB
		f_2 = 500 MHz, V_O = 100 dB $\mu/75~\Omega$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. *: See measurement circuit



Publication date: March 2003



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